Silicon Carbide Schottky Diode

650 V, 8 A

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 33 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter		Symbol	Value	Unit
Peak Repetitive Reverse Voltage		V_{RRM}	650	V
Single Pulse Avalanche Energy (T $_J$ = 25°C, I $_{L(pk)}$ = 11.5 A, L = 0.5 mH, V = 50 V)		E _{AS}	33	mJ
Continuous Rectified Forward Current	T _C < 153	IF	8.0	Α
Current	T _C < 135		11.6	
Non-Repetitive Peak Forward Surge Current	$T_C = 25^{\circ}C$, $t_P = 10 \mu s$	I _{FM}	577	Α
	$T_{C} = 150^{\circ}C,$ $t_{P} = 10 \mu s$		538	
Non-Repetitive Forward Surge Current (Half-Sine Pulse)	$T_{C} = 25^{\circ}C$ $t_{P} = 8.3 \text{ ms}$	I _{FSM}	42	Α
Power Dissipation	T _C = 25°C	P _{tot}	91	W
	T _C = 150°C		15	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE

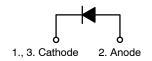
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.64	°C/W



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V _{RRM}	I _F	
650 V	8.0 A	

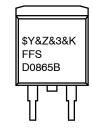


Schottky Diode



DPAK3 (TO-252, 3 LD) CASE 369AS

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code

&3 = Numeric Date Code

&K = Lot Code

FFSD0865B = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
ON CHARAC	TERISTICS			-		
V _F	Forward Voltage	I _F = 8.0 A, T _J = 25°C		1.39	1.7	V
		I _F = 8.0 A, T _J = 125°C		1.55	2.0	
		I _F = 8.0 A, T _J = 175°C		1.71	2.4	1
I _R Reverse C	Reverse Current	V _R = 650 V, T _J = 25°C		0.5	40	μΑ
		V _R = 650 V, T _J = 125°C		1.0	80	
		V _R = 650 V, T _J = 175°C		2.0	160	
HARGES, C	APACITANCES & GATE RES	ISTANCE		-		
Q_C	Total Capacitive Charge	V _C = 400 V		22		nC
C _{tot}	7	V _R = 1 V, f = 100 kHz		336		pF
		V _R = 200 V, f = 100 kHz		39		1
		V _R = 400 V, f = 100 kHz		30		1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PART MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method [†]	Reel Size	Tape Width	Quantity
FFSD0865B	FFSD0865B	DPAK	Tape & Reel	330 mm	16 mm	2500 units

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL CHARACTERISTICS

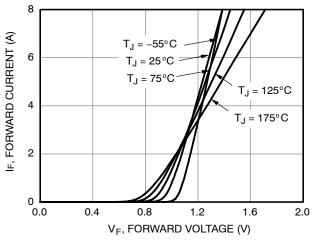
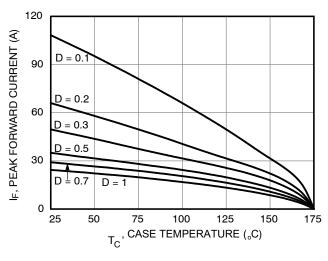


Figure 1. Forward Characteristics

Figure 2. Reverse Characteristics



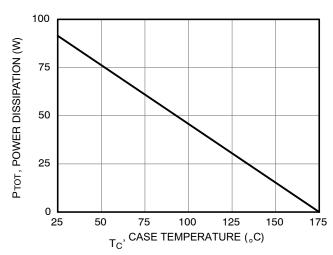
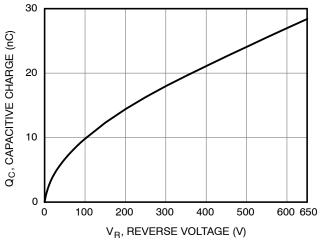


Figure 3. Current Derating

Figure 4. Power Derating



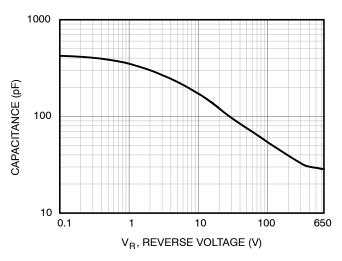


Figure 5. Capacitive Charge vs. Reverse Voltage

Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS

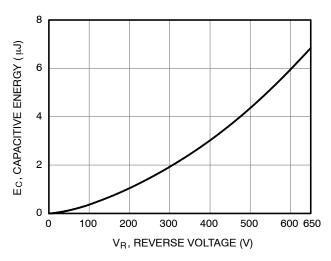


Figure 7. Capacitance Stored Energy

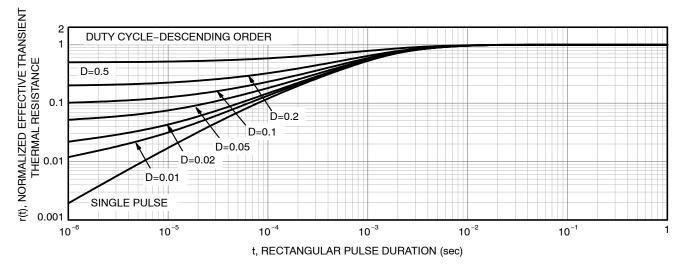


Figure 8. Junction-to-Case Transient Thermal Response

PACKAGE DIMENSIONS

DPAK3 (TO-252 3 LD) CASE 369AS Α ISSUE O 6.73 6.35 5.46 5.21 −5.55 MIN→ 6.22 5.97 6.50 MIN 0.25 MAX PLASTIC BODY C 2 3 STUB DIODE PRODUCTS VERSION 1.14 0.76 3 (0.59)-1.25 MIN 0.89 0.64 ⊕ 0.25 M AM C 2.29 4.57 LAND PATTERN RECOMMENDATION NON-DIODE PRODUCTS VERSION 2.39 SEE 2.18 4.32 MIN NOTE D 0.58 0.45 5,21 MIN 10.41 9.40 SEE DETAIL A NON-DIODE PRODUCTS VERSION DIODE PRODUCTS VERSION ○ 0.10 B 0.51 **GAGE PLANE** NOTES: UNLESS OTHERWISE SPECIFIED A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, 0.61 0.45 ISSUE C, VARIATION AA. ISSUE C, VARIATION AA. B) ALL DIMENSIONS ARE IN MILLIMETERS. C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009. D) SUPPLIER DEPENDENT MOLD LOCKING HOLES OR CHAMFERED CORNERS OR EDGE PROTRUSION. E) TRIMMED CENTER LEAD IS PRESENT ONLY FOR DIODE PRODUCTS (1.54)10° 0° 1.78 F) DIMENSIONS ARE EXCLUSSIVE OF BURSS, 0.127 MAX 1.40 MOLD FLASH AND TIE BAR EXTRUSIONS. **SEATING PLANE** G) LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD (2.90)

DETAIL A (ROTATED -90°) SCALE: 12X

TO228P991X239-3N.

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